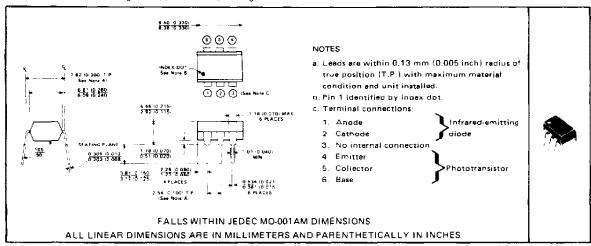
COMPATIBLE WITH STANDARD TTL INTEGRATED CIRCUITS

- Gallium Arsenide Diode Infrared Source Optically Coupled to a Silicon N-P-N Phototransistor
- High Direct-Current Transfer Ratio
- High-Voltage Electrical Isolation . . . 1.5-kV or 2.5-kV Rating
- Plastic Dual-In-Line Package
- High-Speed Switching: $t_r = 5 \mu s$, $t_f = 5 \mu s$ Typical

mechanical data

The package consists of a gallium arsenide infrared-emitting diode and an n-p-n sition phototransistor mounted on a 6-lead frame encapsulated within an electrically nonconductive plastic compound. The case will withstand soldering temperature with no deformation and device performance characteristics remain stable when operated in high-humidity conditions. Unit weight is approximately 0.52 grams.



absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)

Imput-to-Output Voltage: TIL111			±1.5 kV
TIL114, TIL116, TIL117			±2.5 kV
Collector Base Voltage			. 70 V
Collector Emitter Voltage (See Note 1)			. 30 V
Emitter-Collector Voltage			. 7 V
Emitter Base Voltage			. 7 V
Input-Diode Reverse Voltage			. 3 V
Input Diode Continuous Forward Current at (or below) 25°C Free Air Temperature (See Note 2)			100 mA
Continuous Power Dissipation at (or below) 25°C Free-Air Temperature.			
Infrared-Emitting Diode (See Note 3)			150 mW
Phototransistor (See Note 4)			150 mW
Total, Infrared-Emitting Diode plus Phototransistor (See Note 5)			250 mW
Storage Temperature Range	-5	5 6	to 150°C

NOTES: 1. This value applies when the base emitter diode is open-circuited

- Inisization applies when the pase emitter globe is open directined.
 Derate linearly to 100°C free air temperature at the rate of 1.33 mA/ C.
- Derate linearly to 100°C free air temperature at the rate of 2 mW/C.
 Derate linearly to 100°C free air temperature at the rate of 2 mW/C.
- 5. Derate linearly to 100°C free air temperature at the rate of 3.33 mW/°C



TIL111, TIL114, TIL116, TIL117 OPTOCOUPLERS

electrical characteristics at 25°C free-air temperature

	PARAMETER Collector Base Breakdown Voltage		RAMETER TEST CONDITIONS		TIL111 TIL114			TIL116			TIL117			UNIT
					MIN TYP MAX		MIN	TYP	MAX	MIN	TYP	MAX	1	
VIBR)CBO			I _C = 10 μA, I _F = 0	1 _E = 0,	70			70			70			V
VIBR)CEO	Collector- Breakdow		I _C = 1 mA, I _F = 0	18 = 0'	30			30			30			٧
V(8R)E80	Emitter-Base Breakdown Voltage		le = 10 μA, le = 0	I _C = 0,	7			7			7			V
I _B	Input Diode Static Reverse Current		V _R = 3 V			•	10	i i		10			10	μА
	On-State Collector Current	Phototransistor Operation	V _{CE} = 0.4 V, I _B = 0 V _{CE} = 10 V,		2	7					ļ ———			mA
(Clan)			1B = 0					2	5		5	9		
		Photodiode Operation	V _{CB} = 0.4 V, I _E = 0		7	20		7	20		7	20		μА
	Off-State Collector Current	Phototransistor Operation	IB = 0			1	50		1	50	l l	1	50	nA.
¹ C(off)		Photodiode Operation	V _{CB} = 10 V, I _E = 0	IF = 0,		01	20		0.1	20		0.1	20] '"'
	Transistor Static		VCE = 5 V. I _F = 0	_	100	300					200	550		
pEE	Transfer F		V _{CE} = 5 V, _F = 0	I _C = 100 μA,			"	100	300					
٧ _F	Input Diode Static Forward Voltage		1p = 16 mA			1.2	1.4		1.25	1.5	Ī	1.2	1.4	v
VCE(sat)	Collector-Emitter		ic = 2 mA, le = 0	ic = 16 mA,		0.25	0.4							:
			IC = 2.2 mA, IB = 0						0.25	04	-			· v
			1 _C = 0.5 mA, 1 _B = 0									0.25	0.4	
10	Input-to-Output Internal Resistance			kV for TIL111, kV for all others,	1011			1013			1011			23
Cio	Input to Capacitan	-	V _{in-out} = 0, See Note 6	f = 1 MHz,		1	1 3		1	1.3		1	1.3	pF

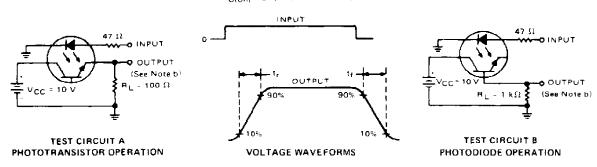
NOTE 6. These parameters are measured between both input diode leads shorted together and all the phototransistor leads shorted together

switching characteristics at 25°C free-air temperature

	PARAMETER		TEST CONDITIONS		TIL111 TIL114			T1L116			TIL117		
					V TYP	MAX	MIN	N TYP	MAX	MIN	TYP	MAX	1
1,	Rise Time	Phototransistor	$V_{CC} = 10 \text{ V}, I_{C(D\Pi)} = 2 \text{ mA},$ $R_1 = 100 \Omega,$		5	10		5	10		5	10	
ī ļ	Fall Time	Operation	See Test Circuit A of Figure 1		5	10		5	10		5	10	μς
t _r	Rise Time	Photodrode	$V_{CC} = 10 \text{ V}, I_{C(on)} = 20 \mu\text{A}$ $R_1 = 1 \text{k}\Omega,$		1			1			1		
tf	Fall Time	Operation	See Test Circuit B of Figure 1		1			1			1		μѕ

PARAMETER MEASUREMENT INFORMATION

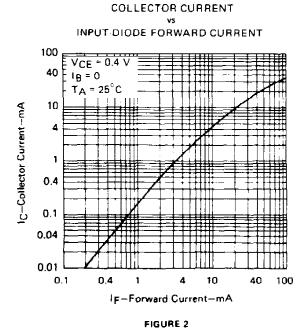
Adjust amplitude of input pulse for: I_{C(on)} = 2 mA (Test Circuit A) or I_{C(on)} = 20 µA (Test Circuit B)



- NOTES: a. The input waveform is supplied by a generator with the following characteristics: $Z_{\text{out}} = 50 \,\Omega_{\odot}$ t, fig. 15 ns, duty cycle $\approx 1\%$,
 - b. The output waveform is monitored on an oscilloscope with the following characteristics: $t_{\rm r} \approx 12$ ns, $R_{\rm in} \approx 1$ M Ω , $C_{\rm in} \approx 20$ pF.

FIGURE 1-SWITCHING TIMES

TYPICAL CHARACTERISTICS



TIL111, TIL114

TIL116, TIL117

COLLECTOR CURRENT

vs

INPUT-DIODE FORWARD CURRENT

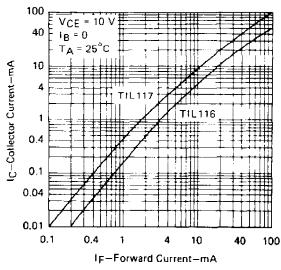


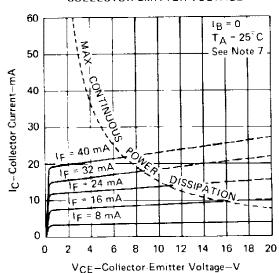
FIGURE 3

TYPICAL CHARACTERISTICS

TIL111, TIL114

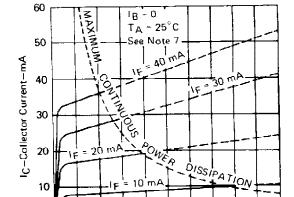
COLLECTOR CURRENT

COLLECTOR-EMITTER VOLTAGE



TIL117 COLLECTOR CURRENT vs COLLECTOR-EMITTER VOLTAGE

FIGURE 4



6 8

O

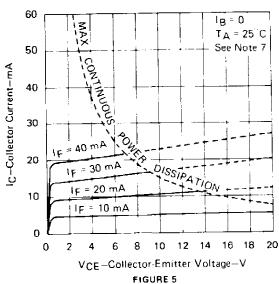
0

VCE-Collector-Emitter Voltage--V FIGURE 6

TIL116

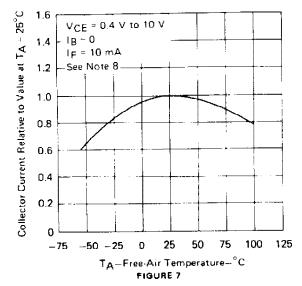
COLLECTOR CURRENT

COLLECTOR-EMITTER VOLTAGE



RELATIVE ON-STATE COLLECTOR CURRENT

FREE-AIR TEMPERATURE



NOTES: 7 Pulse operation of input diode is required for operation beyond limits shown by dotted lines

10 12 14 16 17 20

B. These parameters were measured using pulse techniques $t_{\rm W}$ = 1 ms, duty cycle $\leq 2\%$

TYPICAL CHARACTERISTICS

OFF-STATE COLLECTOR CURRENT FREE-AIR TEMPERATURE 10 000 V_CE = 10 V 4 000 F 1B = 0 1F = 0 (C(oft) - Off-State Collector Current 1 000 400 100 40 10 4 0.4 0.1 0 40 50 60 70 80 TA- Free Air Temperature-C

FIGURE 8

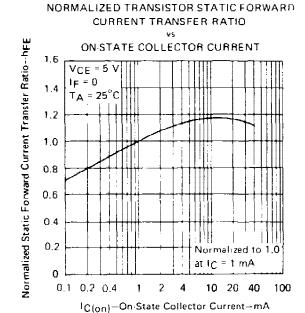
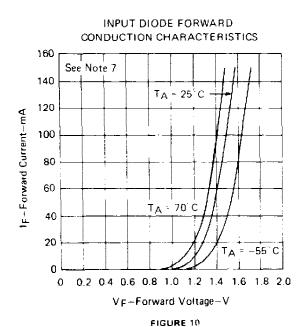
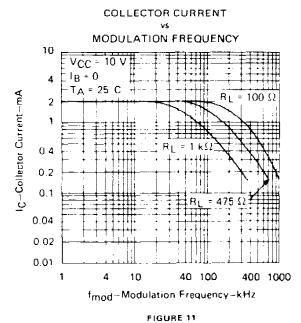


FIGURE 9





NOTE 7: These parameters were measured using pulse techniques, $t_{\rm W}=1$ ms, duty cycle $\sim 2\%$

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